

PATENT ABSTRACTS OF JAPAN

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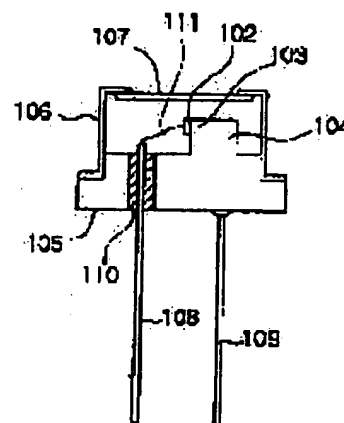
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(54) CASE FOR SEMICONDUCTOR

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a semiconductor for a case which can have a long-term reliability of a semiconductor element and can be manufactured inexpensively.

SOLUTION: The case for a semiconductor includes a heat sink 104 having a semiconductor element 102 mounted thereon, a circular disk 105 for supporting the heat sink 104, and a cap 106 for covering the heat sink 104 and a mount part having the semiconductor element 102 mounted thereon to be joined to the disk 105 and to define a sealed space therein. In this case, the mount part, heat sink 104 and disk 105 are integrally compressed and molded with tungsten/ copper composite powder having a suitable weight ratio of tungsten and copper powder to form a molded body, and the compressed and molded body is sintered.



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